



Material Content Data Sheet



Sales Product Name	TLD7396EK			Issued		29. August 2013		
MA#	MA000969180							
Package	PG-DSO-14-43			Weight*		149.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.255	2.84	2.84	28430	28430
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		465	
	non noble metal	iron	7439-89-6	1.392	0.93		9300	
	non noble metal	copper	7440-50-8	56.512	37.76	38.75	377618	387499
wire	non noble metal	copper	7440-50-8	0.469	0.31	0.31	3132	3132
encapsulation	organic material	carbon black	1333-86-4	0.166	0.11		1111	
	plastics	epoxy resin	-	7.646	5.11		51089	
	inorganic material	silicondioxide	60676-86-0	75.292	50.31	55.53	503110	555310
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8193	8193
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9472	9472
glue	plastics	epoxy resin	-	0.298	0.20		1991	
	noble metal	silver	7440-22-4	0.894	0.60	0.80	5973	7964
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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